

AMENDMENTS TO THE CLAIMS

This listing of claims will replace all prior versions and listings of claims in the application:

Listing of Claims:

C3b 1 1. (Previously Amended) A semiconductor device,
2 comprising:
3 a semiconductor region formed in a semiconductor
4 substrate;
5 a plurality of basic cells regularly arranged on said
6 semiconductor substrate;
7 a plurality of field effect transistors arranged in
8 each of a plurality of said basic cells and formed in said
9 semiconductor region;
10 power supply wirings arranged for supplying power
11 supply voltages to a plurality of said field effect
12 transistors; and
13 switch elements provided between said semiconductor
14 region and said power supply wirings,
15 wherein said switch elements include field effect
16 transistors of said basic cells.

Claims 2 - 6 (Cancelled)

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1 7. (Currently Amended) A semiconductor device,
2 comprising:
3 a semiconductor region formed in a semiconductor
4 substrate;
5 a plurality of basic cells regularly arranged on said
6 semiconductor substrate;
7 a plurality of field effect transistors arranged in
8 each of a plurality of said basic cells and formed in said
9 semiconductor region;
10 power supply wirings arranged for supplying the power
11 supply voltages to a plurality of said field effect
12 transistors; and
13 switch elements provided between said semiconductor
14 region and said power supply wirings;
15 wherein said switch elements ~~are formed of the~~ include
16 field effect transistors ~~in~~ of said basic cells and are
17 discretely arranged in said semiconductor region.

1 8. (Currently Amended) A semiconductor device,
2 comprising:

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3 a semiconductor region formed in a semiconductor
4 substrate;
5 a plurality of basic cells regularly arranged ~~in~~ on
6 said semiconductor substrate;
7 a plurality of field effect transistors arranged in
8 each of a plurality of said basic cells and formed in said
9 semiconductor region;
10 power supply wirings arranged for supplying the power
11 supply voltages to said field effect transistors; and
12 switch elements provided between said semiconductor
13 region and said power supply wirings,
14 wherein said switch elements ~~are formed of~~ include
15 field effect transistors of said basic cells, and wherein a
16 semiconductor region, which is formed within said
17 semiconductor region in a plurality of said basic cells,
18 and of the a conductivity type opposed to that of said
19 semiconductor region, and is electrically connected to said
20 power supply wirings ~~are electrically connected~~.

1 9. (Currently Amended) A semiconductor device,
2 comprising:
3 a semiconductor region formed in a semiconductor
4 substrate;

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5 a plurality of basic cells regularly arranged on said
6 semiconductor substrate;

7 a plurality of field effect transistors arranged in
8 each of a plurality of basic cells and are formed in said
9 semiconductor region;

10 power supply wirings arranged for supplying the power
11 supply voltages to said field effect transistors; and

12 switch elements provided between said semiconductor
13 region and said power supply wirings,

14 wherein said switch elements ~~are formed of the~~ include
15 field effect transistors of said basic cells, and at least
16 one of a pair of semiconductor regions for source and drain
17 of unused field effect transistors of said field effect
18 transistors and said power supply wirings are electrically
19 connected.

1 10. (Currently Amended) A semiconductor device,
2 comprising:

3 a semiconductor region formed in a semiconductor
4 substrate;

5 a plurality of basic cells regularly arranged ~~in~~ on
6 said semiconductor substrate;

7 a plurality of field effect transistors arrang d in

c³¹ 8 each of a plurality of said basic cells and formed in said
9 semiconductor region;
10 power supply wirings arranged for supplying the power
11 supply voltages to said field effect transistors; and
12 switch elements provided between said semiconductor
13 region and said power supply wirings,
14 wherein said switch elements ~~are formed of said~~
15 include field effect transistors of said basic cells and
16 are discretely arranged within said semiconductor region,
17 and
18 wherein a semiconductor region, formed in said
19 semiconductor region of a plurality of basic cells, and of
20 ~~the~~ a conductivity type opposed to that of said
21 semiconductor region, and said power supply wirings are
22 electrically connected.

1 11. (Currently Amended) A semiconductor device,
2 comprising:
3 a semiconductor region formed in a semiconductor
4 substrate;
5 a plurality of basic cells regularly arranged ~~in~~ on
6 said semiconductor substrate;

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7 a plurality of field effect transistors arranged in
8 each of a plurality of said basic cells and ~~are~~ formed in
9 said semiconductor region;
10 power supply wirings arranged for supplying the power
11 supply voltages to said field effect transistors; and
12 switch elements provided between said semiconductor
13 region and said power supply wirings,
14 wherein said switch elements ~~are formed of said~~
15 include field effect transistors of said basic cells and
16 are discretely arranged within said semiconductor region,
17 and
18 wherein at least one of a pair of semiconductor
19 regions for source and drain of unused field effect
20 transistors of said field effect transistors and said power
21 supply wirings are electrically connected.

1 12. (Currently Amended) A semiconductor device,
2 comprising:

3 a semiconductor region formed in a semiconductor
4 substrate;

5 a plurality of basic cells regularly arranged in on
6 said semiconductor substrate;

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7 a plurality of field effect transistors arranged in
8 each of a plurality of said basic cells and formed in said
9 semiconductor region;
10 power supply wirings arranged for supplying the power
11 supply voltages to said field effect transistors; and
12 switch elements provided between said semiconductor
13 region and said power supply wirings,
14 wherein said switch elements ~~are formed of said~~
15 include field effect transistors of said basic cells and
16 are discretely arranged in said semiconductor region, and
17 wherein at least one of a pair of semiconductor
18 regions for source and drain of unused field effect
19 transistors arranged between the switch elements discretely
20 arranged in said semiconductor region among said field
21 effect transistors and said power supply wirings are
22 electrically connected.

1 13. (Currently Amended) A semiconductor device,
2 comprising:

3 a semiconductor region formed in a semiconductor
4 substrate;

5 a plurality of basic cells regularly arranged ~~in~~ on
6 said semiconductor substrate;

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7 a plurality of field effect transistors arranged in
8 each of a plurality of said basic cells and formed in said
9 semiconductor region;

10 circuits formed of a plurality of said basic cells;

11 power supply wirings arranged for supplying the power
12 supply voltages to said field effect transistors; and

13 switch elements provided between said semiconductor
14 region and said power supply wirings,

15 wherein said switch elements are built in ~~the~~ a
16 predetermined circuit among said circuits.

1 14. (Currently Amended) A semiconductor device,
2 comprising:

3 a semiconductor region formed in a semiconductor
4 substrate;

5 a plurality of basic cells regularly arranged ~~in~~ on
6 said semiconductor substrate;

7 a plurality of field effect transistors arranged in
8 each of a plurality of said basic cells and formed in said
9 semiconductor region;

10 circuits formed of a plurality of said basic cells;

11 power supply wirings arranged for supplying the power
12 supply voltages to said field effect transistors; and

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13 switch elements provided between said semiconductor
14 region and said power supply wirings,
15 wherein said circuits include ~~the~~ a circuit to in
16 which said switch elements are built in and ~~the~~ a circuit
17 ~~to in~~ in which said switch elements are not built in.

1 15. (Currently Amended) A semiconductor device as
2 claimed in claim 13 or 14, wherein a semiconductor region,
3 ~~of the conductivity type opposed to that of said~~
4 ~~semiconductor region,~~ formed in said semiconductor region
5 of a plurality of said basic cells and of a conductivity
6 type opposed to that of said semiconductor region, and said
7 power supply wirings are electrically connected.

1 16. (Original) A semiconductor as claim in claim 13
2 or 14, wherein at least one of a pair of semiconductor
3 regions for source and drain of unused field effect
4 transistors among said field effect transistors and said
5 power supply wirings are electrically connected.

1 17. (Previously Amended) A semiconductor device as
2 claimed in claim 13 or 14, wherein said circuits are logic
3 circuits and said switch elements are discretely arranged

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4 in said semiconductor substrate.

1 18. (Original) A semiconductor device as claimed in
2 claim 16, wherein said unused field effect transistors are
3 field effect transistors of basic cells not forming logic
4 circuits and said unused basic cells are formed among said
5 switch elements.

1 19. (Currently Amended) A semiconductor device as
2 claimed in claim 13 or 14, wherein said circuit ~~comprising~~
3 in which the switch elements are built in is a clock
4 circuit or a flip-flop circuit.

1 20. (Currently Amended) A semiconductor device as
2 claimed in claim 13 or 14, wherein said switch elements are
3 ~~formed of~~ include field effect transistors ~~in~~ of said basic
4 cells.

1 21. (Currently Amended) A semiconductor device as
2 claimed in any one of claims 7 to 14, wherein said basic
3 cells include the p-channel type field effect transistors
4 and n-channel type field effect transistors.

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1 22. (Previously Amended) A semiconductor device as
2 claimed in any one of claims 7 to 12, further comprising:
3 a first wiring layer formed over said switch elements;
4 a second wiring layer formed over said first wiring
5 layer and having wiring extending in a direction transverse
6 to wiring of said first wiring layer; and
7 a third wiring layer formed over said second wiring
8 layer and having wiring extending in a direction transverse
9 to wiring of said second wiring layer,
10 wherein a wiring electrically connected to gate
11 electrodes of said switch elements is formed of wiring of
12 the third wiring layer and arranged in parallel to said
13 power supply wirings.

1 23. (Previously Amended) A semiconductor device as
2 claimed in any one of claims 7 to 14, wherein a
3 semiconductor region for power feeding to supply a
4 predetermined voltage to the semiconductor region formed in
5 said semiconductor substrate is formed in a region between
6 an internal circuit region where a plurality of said basic
7 cells are arranged and a peripheral circuit region at an
8 external side of said internal circuit region.

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1 24. (Original) A semiconductor device as claimed in
2 claim 23, wherein a wiring for supplying the predetermined
3 voltage to said semiconductor region for power feeding is
4 arranged to surround said internal circuit region.

1 25. (Currently Amended) A semiconductor device as
2 claimed in claim 24, wherein the wiring for supplying the
3 predetermined voltage to said semiconductor region for
4 power feeding is electrically connected to ~~the~~ a terminal
5 for testing via ~~the~~ an external terminal of the
6 semiconductor device.

1 26. (Currently Amended) A semiconductor device as
2 claimed in claim 24, wherein the wiring for supplying the
3 predetermined voltage to said semiconductor region for
4 power feeding is electrically connected to ~~the~~ wiring for
5 power feeding arranged like a lattice within said internal
6 circuit region.

1 27. (Currently Amended) A semiconductor device as
2 claimed in any one of claims 1 and 7 to 14, wherein said
3 switch elements are turned ON in ~~the~~ a normal operation
4 period of the semiconductor device and ~~the~~ a power supply

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5 voltage is applied from said power supply wirings to the
6 semiconductor region formed in said semiconductor
7 substrate, and said switch elements are turned OFF in the a
8 testing or waiting period of the semiconductor device and
9 the a voltage different from said power supply voltage is
10 applied to said semiconductor region.

1 28. (Currently Amended) A semiconductor device,
2 comprising:

3 a first semiconductor region formed in a semiconductor
4 substrate;

5 a second semiconductor region formed in said
6 semiconductor substrate to have a conductivity type opposed
7 to that of said first semiconductor region;

8 a plurality of basic cells regularly arranged ~~in~~ on
9 said semiconductor substrate;

10 a first field effect transistors formed in said first
11 semiconductor region as the field effect transistors of
12 said basic cells;

13 a second field effect transistors formed in said
14 second semiconductor region as the field effect transistors
15 of said basic cells and to have the a conductivity type
16 opposed to that of said first field effect transistors ;

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17 a first power supply wiring connected to said first
18 field effect transistors;

19 a second power supply wiring connected to said second
20 field effect transistors to supply a potential which is
21 relatively lower than the a potential of said first power
22 supply wiring;

23 first switch elements provided between said first
24 semiconductor region and said first power supply wiring;
25 and

26 second switch elements provided between said second
27 semiconductor region and said second power supply wiring,

28 wherein said first switch elements are formed of the
29 first field effect transistors in said basic cells and
30 discretely arranged within said first semiconductor region,
31 and

32 wherein said second switch elements are formed of the
33 second field effect transistors in said basic cells and
34 discretely arranged within said second semiconductor
35 region.

1 29. (Currently Amended) A semiconductor device,
2 comprising:

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3 a first semiconductor region formed in a semiconductor
4 substrate;

5 a second semiconductor region formed in said
6 semiconductor substrate to have a conductivity type opposed
7 to that of said first semiconductor region;

8 a plurality of basic cells regularly arranged ~~in~~ on
9 said semiconductor substrate;

10 a first field effect transistors formed in said first
11 semiconductor region as ~~the~~ field effect transistors ~~in~~ of
12 said basic cells;

13 a second field effect transistors ~~as the field effect~~
14 ~~transistor in said basic cells,~~ formed in said second
15 semiconductor region as field effect transistors of said
16 basic cells and to have ~~the~~ a conductivity type opposed to
17 that of said first field effect transistors ;

18 a first power supply wiring connected to said first
19 field effect transistors ;

20 a second power supply wiring connected to said second
21 field effect transistors to supply ~~the~~ a potential which is
22 relatively lower than that of said first power supply
23 wiring;

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24 a first switch elements provided between said first
25 semiconductor region and said first power supply wiring;
26 and
27 a second switch elements provided between said second
28 semiconductor region and said second power supply wiring,
29 wherein said first switch elements include ~~is formed~~
30 of the first field effect transistors in the predetermined
31 basic cells among a said plurality of said basic cells,
32 wherein said second switch elements include ~~is formed~~
33 of the second field effect transistors in the predetermined
34 basic cells among a said plurality of said basic cells,
35 wherein the a region formed in said first
36 semiconductor region in a plurality of said basic cells
37 electrically connects the semiconductor region of the
38 conductivity type opposed to that of said first
39 semiconductor region and said first power supply wiring,
40 and
41 wherein the a region formed in said second
42 semiconductor region in a plurality of basic cells
43 electrically connects the semiconductor region of the
44 conductivity type opposed to that of said second
45 semiconductor region and said second power supply wiring.

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1 30. (Currently Amended) A semiconductor device,
2 comprising:

3 a first semiconductor region formed in a semiconductor
4 substrate;

5 a second semiconductor region formed in said
6 semiconductor substrate to have a conductivity type opposed
7 to that of said first semiconductor region;

8 a plurality of basic cells regularly arranged ~~in~~ on
9 said semiconductor substrate;

10 a first field effect transistorsu formed in said first
11 semiconductor region as ~~the~~ field effect transistorsu of
12 said basic cells;

13 a second field effect transistorsu, ~~as the field effect~~
14 ~~transistor of said basic cells~~, formed in said second
15 semiconductor region as field effect transistors of said
16 basic cells and to have ~~the~~ a conductivity type opposed to
17 that of said first field effect transistorsu;

18 a first power supply wiring connected to said first
19 effect transistorsu;

20 a second power supply wiring connected to said second
21 field effect transistorsu to supply ~~the~~ a potential
22 relatively lower than that of said first power supply
23 wiring;

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24 a first switch elements provided between said first
25 semiconductor region and said first power supply wiring;
26 and

27 a second switch elements provided between said second
28 semiconductor region and said second power supply wiring,

29 wherein said first switch elements ~~include is formed~~
30 of the first field effect transistors in the predetermined
31 basic cells among a said plurality of said basic cells,

32 wherein said second switch elements ~~include is formed~~
33 of the second field effect transistors in the predetermined
34 basic cells among a said plurality of said basic cells,

35 wherein at least one of a pair of semiconductor
36 regions for source and drain of unused first field effect
37 transistors among said first field effect transistors is
38 electrically connected to said first power supply wiring,
39 and

40 wherein at least one of a pair of semiconductor
41 regions for source and drain of unused second field effect
42 transistors among a ~~plurality of~~ said second field effect
43 transistors is electrically connected said second power
44 supply wiring.

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1 31. (Currently Amended) A semiconductor device,
2 comprising:

3 a first semiconductor region formed in a semiconductor
4 substrate;

5 a second semiconductor region formed in said
6 semiconductor substrate to have the a conductivity type
7 opposed to that of said first semiconductor region;

8 a plurality of basic cells regularly arranged ~~in~~ on
9 said semiconductor substrate;

10 a first field effect transistors formed in said first
11 semiconductor region as ~~the~~ field effect transistors of
12 said basic cells;

13 a second field effect transistors formed, ~~as the field~~
14 ~~effect transistor of said basic cell,~~ in said second
15 semiconductor region as field effect transistors of said
16 basic cells and to have the a conductivity type opposed to
17 that of said first field effect transistors ;

18 a first power supply wiring connected to said first
19 field effect transistors ;

20 a second power supply wiring connected to said second
21 field effect transistors to supply the a potential
22 relatively lower than that of said first power supply
23 wiring;

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24 a first switch elements provided between said first
25 semiconductor region and said first power supply wiring;
26 and

27 a second switch elements provided between said second
28 semiconductor region and said second power supply wiring,

29 wherein said first switch elements include ~~are formed~~
30 of the first field effect transistors in the predetermined
31 basic cells among a said plurality of ~~said~~ basic cells and
32 are discretely arranged in said first semiconductor region,

33 wherein said second switch elements include ~~are formed~~
34 of the second field effect transistors in the predetermined
35 basic cells among a said plurality of ~~said~~ basic cells and
36 are discretely arranged in said ~~first~~ second semiconductor
37 region,

38 wherein ~~the~~ a region formed in said first
39 semiconductor region in a plurality of said basic cells
40 electrically connects the semiconductor region of the
41 conductivity type opposed to that of said first
42 semiconductor region and said first power supply wiring,
43 and

44 wherein ~~the~~ a region formed in said second
45 semiconductor region in a plurality of said basic cells
46 electrically connects the semiconductor region of th

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47 conductivity type opposed to that of said second
48 semiconductor region and said second power supply wiring.

1 32. (Currently Amended) A semiconductor device,
2 comprising:

3 a first semiconductor region formed in a semiconductor
4 substrate;

5 a second semiconductor region formed in said
6 semiconductor substrate to have the a conductivity type
7 opposed to that of said first semiconductor region;

8 a plurality of basic cells regularly arranged ~~in~~ on
9 said semiconductor substrate;

10 a first field effect transistors formed in said first
11 semiconductor region as the field effect transistors of
12 said basic cells;

13 a second field effect transistors formed, ~~as the field~~
14 ~~effect transistor of said basic cells,~~ in said second
15 semiconductor region as field effect transistors of said
16 basic cells and to have the channel ~~of the~~ conductivity
17 type opposed to that of said first field effect
18 transistors ;

19 a first power supply wiring connected to said first
20 field effect transistors ;

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21 a second power supply wiring connected to said second
22 field effect transistors to supply the a potential
23 relatively lower than that of said first power supply
24 wiring;

25 a first switch elements provided between said first
26 semiconductor region and said first power supply wiring;
27 and

28 a second switch elements provided between said second
29 semiconductor region and said second power supply wiring,

30 wherein said first switch elements include ~~are formed~~
31 of the first field effect transistors in the predetermined
32 basic cells among a said plurality of basic cells and are
33 discretely arranged in said first semiconductor region,

34 wherein said second switch elements include ~~are formed~~
35 of the second field effect transistors in the predetermined
36 basic cells among a said plurality of basic cells and are
37 discretely arranged in said ~~first~~ second semiconductor
38 region,

39 wherein at least one of a pair of semiconductor
40 regions for source and drain of unused first field effect
41 transistors among ~~a plurality of~~ said first field effect
42 transistors is electrically connected to said first power
43 supply wiring, and

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44 wherein at least one of a pair of semiconductor
45 regions for source and drain of unused second field effect
46 transistors among a ~~plurality of~~ said second field effect
47 transistors is electrically connected to said second power
48 supply wiring.

1 33. (Currently Amended) A semiconductor device,
2 comprising:

3 first and second semiconductor regions formed in the a
4 peripheral circuit region of a semiconductor substrate;

5 a plurality of cells for input/output circuits
6 regularly arranged in the peripheral circuit region of said
7 semiconductor substrate;

8 a plurality of field effect transistors for
9 input/output circuits arranged in each of a plurality of
10 cells for input/output circuits and formed in said first
11 and second semiconductor regions;

12 power supply wiring arranged for supplying the a power
13 supply voltage to a plurality of said field effect
14 transistors for input/output circuits; and

15 switch elements provided between the second
16 semiconductor region in said p ripheral circuit region and
17 said power supply wiring,

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18 wherein an output circuit electrically connected to
19 the an external terminal includes ~~is formed of the~~ field
20 effect transistors for input/output circuits in said first
21 semiconductor region and an input circuit electrically
22 connected to ~~the~~ an external terminal includes ~~is formed of~~
23 ~~the~~ field effect transistors for input/output circuits in
24 said second semiconductor region, and
25 wherein said switch elements include ~~are formed of the~~
26 field effect transistors not used for the input circuit
27 among the field effect transistors for input/output
28 circuits in said second semiconductor region.

1 34. (Currently Amended) A semiconductor device,
2 comprising:
3 a semiconductor region formed in ~~the~~ a peripheral
4 circuit region of a semiconductor substrate;
5 a plurality of cells for input/output circuits
6 regularly arranged in the peripheral circuit region of said
7 semiconductor substrate;
8 a plurality of field effect transistors for
9 input/output circuits arranged in each of a plurality of
10 cells for input/output circuits and formed in said
11 semiconductor region;

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12 power supply wiring arranged for supplying the a power
13 supply voltage to a plurality of said field effect
14 transistors for input/output circuits; and
15 switch elements provided between the semiconductor
16 region in said peripheral circuit region and said power
17 supply wiring,
18 wherein said peripheral circuit region includes an
19 external region to arrange said field effect transistors
20 for input/output circuits of relatively higher threshold
21 voltage and an internal region to arrange said field effect
22 transistors for input/output circuits of relatively lower
23 threshold voltage, and
24 wherein said switch elements include ~~is formed of the~~
25 field effect transistors not used for input circuit among
26 the field effect transistors for input/output circuits in
27 said internal region.

1 35. (Currently Amended) A semiconductor device as
2 claimed in claim 34, wherein an output circuit includes a
3 ~~is formed of the~~ field effect transistor for input/output
4 circuits in said external region and an input circuit
5 includes a ~~is formed of the~~ field effect transistor for
6 input/output circuits in said internal region.

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1 36. (Currently Amended) A semiconductor device as
2 claimed in claim 33, 34 or 35, wherein ~~the~~ a gate
3 insulation film of the field effect transistor ~~forming of~~
4 said output circuit is thicker than ~~the~~ a gate insulation
5 film of the field effect transistor ~~forming of~~ of said input
6 circuit.

1 37. (Currently Amended) A semiconductor device as
2 claimed in claim 33, 34, or 35, wherein ~~the~~ wiring
3 connected to the gate electrodes of the field effect
4 transistors of ~~forming~~ said switch elements is arranged to
5 surround ~~the~~ said internal circuit region ~~of a~~
6 ~~semiconductor device.~~

1 38. (Previously Amended) A semiconductor device as
2 claimed in any one of claims 33 to 35, wherein at least one
3 of a pair of semiconductor regions for source and drain of
4 the field effect transistors unused for said input/output
5 circuits is electrically connected to said power supply
6 wiring to form a capacitance element.

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1 39. (Currently Amended) A method of manufacturing a
2 semiconductor device, comprising ~~the processes of~~:

3 (a) regularly allocating a plurality of basic cells
4 on a semiconductor substrate;

5 (b) forming a switch element arranged for
6 electrically connecting ~~or~~ and disconnecting the a
7 semiconductor region formed on said semiconductor substrate
8 and the a power supply wiring of the semiconductor device
9 with field effect transistors of predetermined basic cells
10 among said plurality of basic cells; and

11 (c) forming a plurality of circuits with ~~the~~
12 predetermined basic cells among a said plurality of said
13 basic cells.

1 40. (Currently Amended) A method of manufacturing a
2 semiconductor device, comprising ~~the processes of~~:

3 (a) regularly allocating a plurality of basic cells
4 on a semiconductor substrate;

5 (b) forming a switch elements arranged for
6 electrically connecting and disconnecting the a
7 semiconductor region formed on said semiconductor substrate
8 and the a power supply wiring of the semiconductor device

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9 with ~~the~~ field effect transistors of the predetermined
10 basic cells among a said plurality of ~~said~~ basic cells;
11 (c) forming a plurality of circuits with the
12 predetermined basic cells among a said plurality of said
13 basic cells; and
14 (d) allocating a contact hole arranged for
15 electrically connecting at least one of a pair of
16 semiconductor regions for source and drain of unused field
17 effect transistors among ~~a plurality~~ field effect
18 transistors of said basic cells and said power supply
19 wiring.

1 41. (Currently Amended) A method of manufacturing a
2 semiconductor device, comprising the processes of:
3 (a) regularly allocating a plurality basic cells on a
4 semiconductor substrate;
5 (b) forming a switch element arranged for
6 electrically connecting and disconnecting ~~the~~ a
7 semiconductor region formed on said semiconductor substrate
8 and ~~the~~ a power supply wiring of the semiconductor device
9 with ~~the~~ a field effect transistor of ~~the~~ a predetermined
10 basic cells among a said plurality of ~~said~~ basic cells; and

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11 (c) forming a plurality of circuits with the
12 predetermined basic cells among a said plurality of basic
13 cells,

14 wherein said switch element is built in the a
15 predetermined circuit among a said plurality of said
16 circuits in ~~said process step~~ (c).

1 42. (Currently Amended) A method of manufacturing a
2 semiconductor device, comprising ~~the processes of~~:

3 (a) regularly allocating a plurality of basic cells
4 on a semiconductor substrate; and

5 (b) forming a plurality of circuits with the
6 predetermined basic cells among a said plurality of said
7 basic cells,

8 wherein said a switch element is built in the a
9 predetermined circuit among a plurality of said circuits,
10 said switch element including a field effect
11 transistor of a basic cell of said predetermined circuit
12 and being provided between a power supply wiring and a
13 semiconductor region in which field effect transistors of
14 other basic cells of said predetermined circuit are formed.

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1 43. (Currently Amended) A semiconductor device as
2 claimed in claim ~~2, 4, 6~~ or 8, wherein a capacitance
3 element is formed of said semiconductor region and a
4 semiconductor region of ~~the~~ a conductivity type opposed to
5 that of said semiconductor region.

1 44. (Currently Amended) A semiconductor device as
2 claimed in claim ~~3, 5,~~ 9, 11 or 12, wherein a capacitance
3 element is formed of said semiconductor region and at least
4 one of a pair of semiconductor regions for source and drain
5 of said unused field effect transistors.

1 45. (Currently Amended) A semiconductor device as
2 claimed in any one of claims 7 to 12, wherein a logic
3 circuit is formed using said basic cells and said logic
4 circuit is formed among the basic cells ~~forming~~ including
5 said switch elements.

1 46. (Currently Amended) A semiconductor device
2 claimed in claim 9, 11, or 12, wherein a logic circuit is
3 formed using said basic cells, ~~said unused~~ a field effect
4 transistor having said one pair of semiconductor regions is
5 ~~the~~ a field effect transistor of an unused basic cell not

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6 forming a logic circuit, and said logic circuit and unused
7 basic cells are formed among the basic cells forming
8 including said switch elements.
